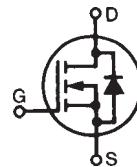


High Voltage Power MOSFET

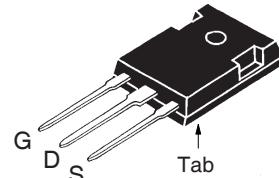
IXTH3N150

V_{DSS} = 1500V
I_{D25} = 3A
R_{DS(on)} ≤ 7.3Ω



N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode

TO-247



G = Gate D = Drain
 S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	1500	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	1500	V
V _{GSS}	Continuous	±30	V
V _{GSM}	Transient	±40	V
I _{D25}	T _C = 25°C	3	A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	9	A
I _A	T _C = 25°C	3	A
E _{AS}	T _C = 25°C	250	mJ
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	5	V/ns
P _D	T _C = 25°C	250	W
T _J		- 55 ... +150	°C
T _{JM}		150	°C
T _{stg}		- 55 ... +150	°C
T _L	Maximum Lead Temperature for Soldering	300	°C
T _{SOLD}	Plastic Body for 10s	260	°C
M _d	Mounting Torque	1.13 / 10	Nm/lb.in.
Weight		6	g

Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 250μA	1500		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.5		5.0 V
I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±100 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			10 μA 100 μA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Note 1			7.3 Ω

Features

- International Standard Package
- Fast Intrinsic Diode
- Avalanche Rated
- Molding Epoxies meet UL 94 V-0 Flammability Classification

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- High Voltage Power Supplies
- Capacitor Discharge Applications
- Pulse Circuits

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1	2.2	3.6	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	1375		pF
		90		pF
		30		pF
R_{GI}	Gate Input Resistance	3.0		Ω
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 5\Omega$ (External)	19		ns
		21		ns
		42		ns
		25		ns
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$	38.6		nC
		6.5		nC
		19.0		nC
R_{thJC}			0.50	$^\circ\text{C}/\text{W}$
R_{thCS}		0.21		$^\circ\text{C}/\text{W}$

TO-247 (IXTH) Outline				
Dim.	Millimeter		Inches	
	min	max	min	max
A	4.70	5.30	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
c	0.38	0.89	0.015	0.035
D	20.79	21.45	0.819	0.845
D1	13.07	-	0.515	-
D2	0.51	1.35	0.020	0.053
E	15.48	16.24	0.610	0.640
E1	13.45	-	0.53	-
E2	4.31	5.48	0.170	0.216
e	5.45 BSC		0.215 BSC	
L	19.80	20.30	0.078	0.800
L1	-	4.49	-	0.177
O P	3.55	3.65	0.140	0.144
O P1	-	7.39	-	0.290
Q	5.38	6.19	0.212	0.244
S	6.14 BSC		0.242 BSC	

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
I_s	$V_{GS} = 0\text{V}$, Note 1		3	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}		12	A
V_{SD}	$I_F = I_s$, $V_{GS} = 0\text{V}$, Note 1		1.3	V
t_{rr} Q_{RM} I_{RM}	$I_F = 1.5\text{A}$, $-\text{di/dt} = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$	0.9		μs
		6.7		μC
		15		A

Note: 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

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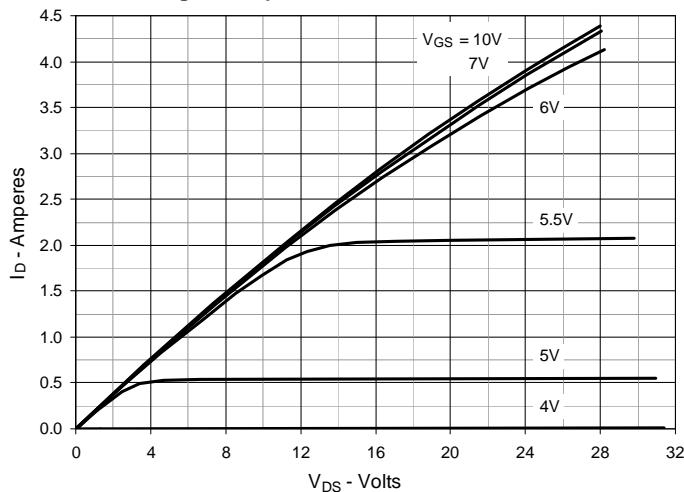
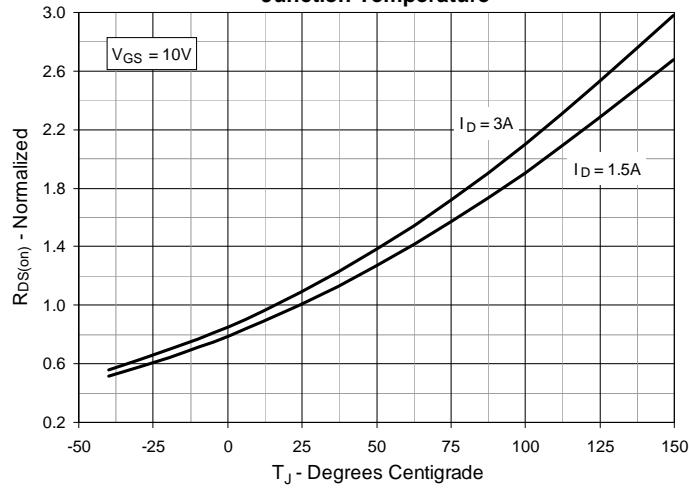
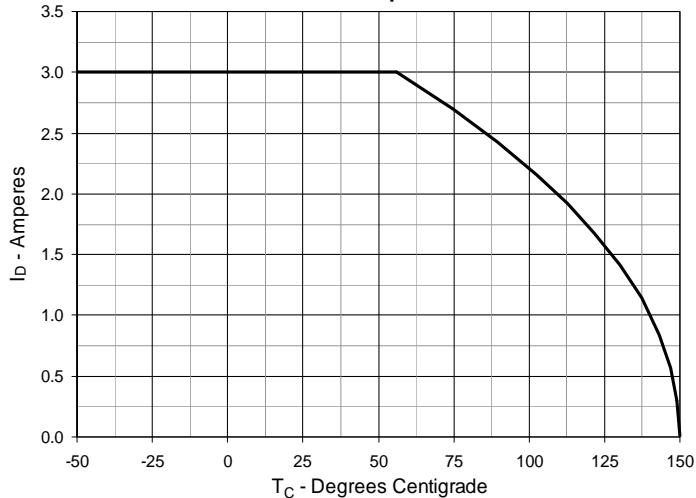
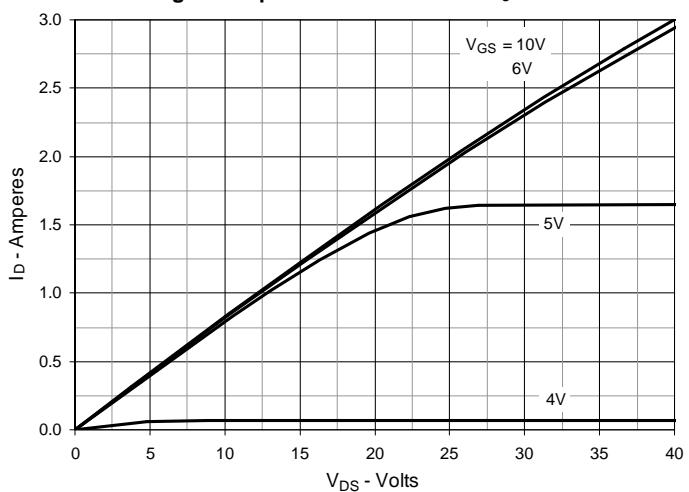
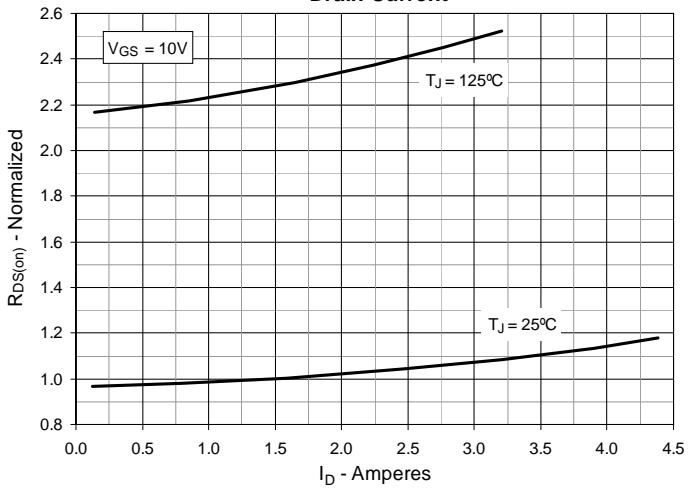
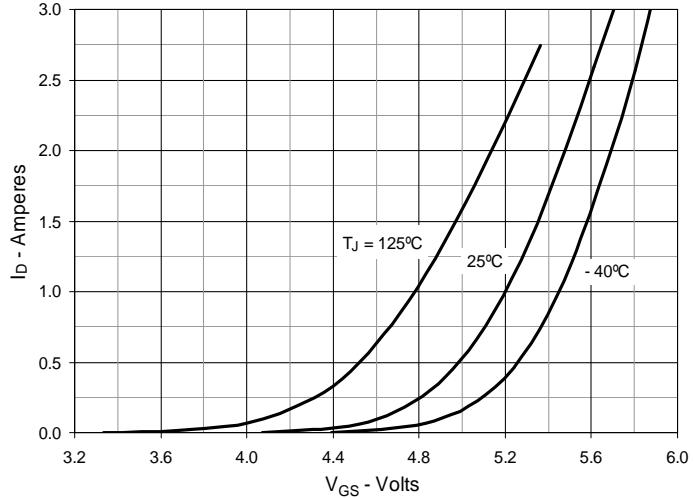
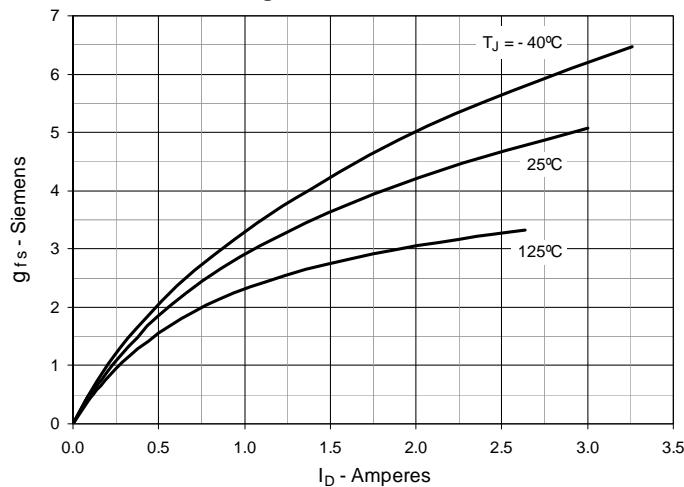
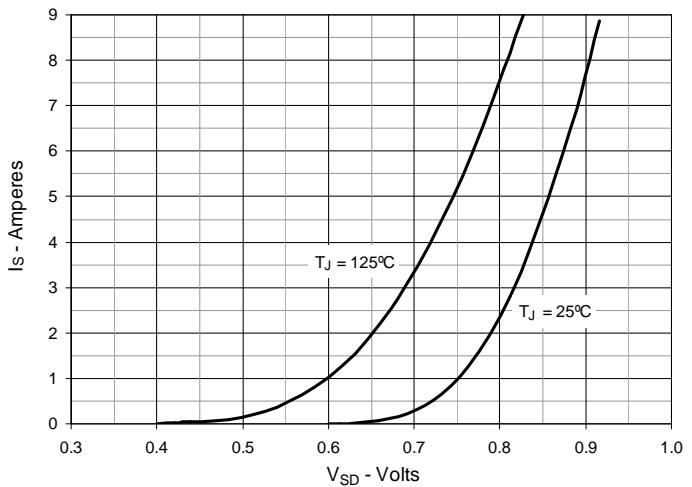
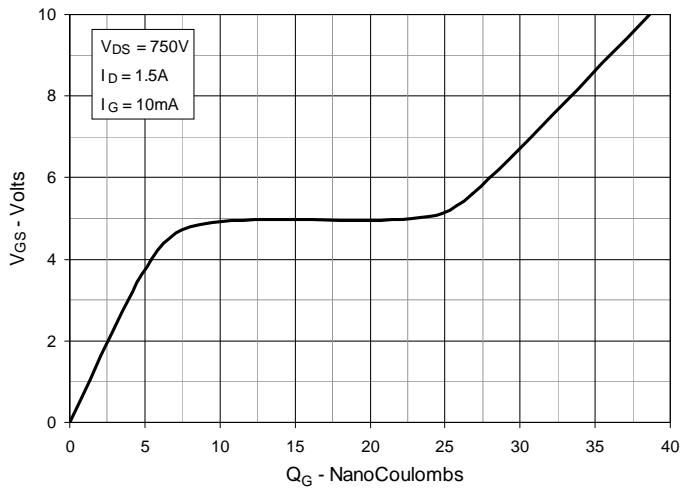
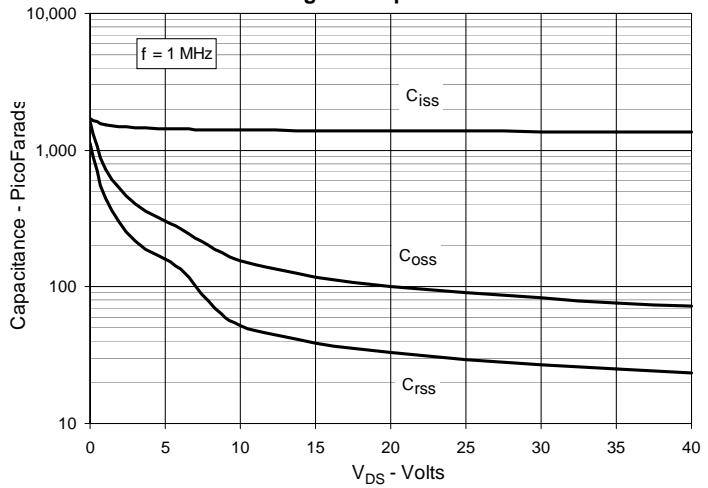
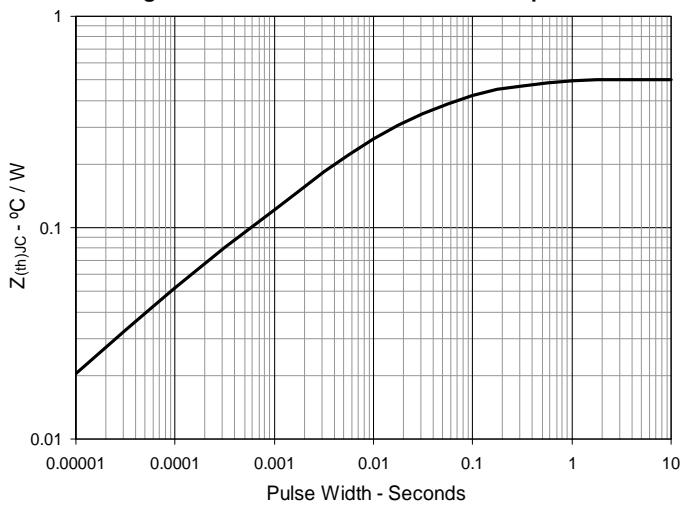
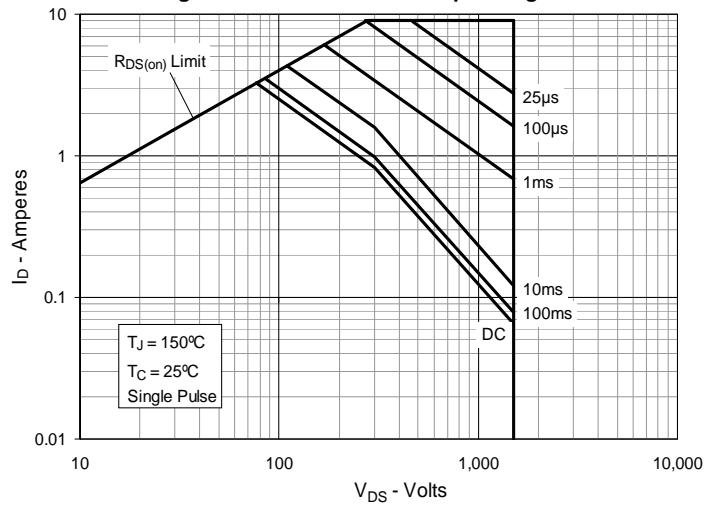
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 3. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Junction Temperature****Fig. 5. Maximum Drain Current vs. Case Temperature****Fig. 2. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Drain Current****Fig. 6. Input Admittance**

Fig. 7. Transconductance**Fig. 8. Forward Voltage Drop of Intrinsic Diode****Fig. 9. Gate Charge****Fig. 10. Capacitance****Fig. 11. Maximum Transient Thermal Impedance****Fig. 12. Forward-Bias Safe Operating Area**

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